

NEW Electroformed Bond Blades
ZP07 SERIES

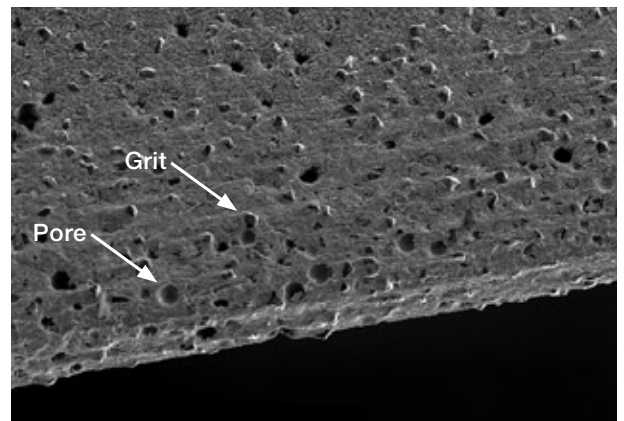
High grade processing is possible with an electroplated porous structure blade



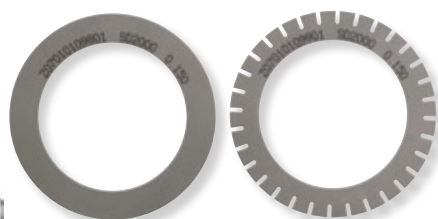
The ZP07 series realizes high-grade processing of hard materials and compound materials by making a porous structure inside the electroplated blade.

The ZP07 series combines high cutting ability that is specific to electroplated bond blades and appropriate self sharpening ability by forming pores in the electroplated bond. Processing of glass and ceramics that were difficult to process with the current electroplated bond is now possible.

- Realizes one-pass processing of glass + Silicon wafer
- Realizes high-grade processing of ceramics



New type of electroplated blade with pores in the blade.



Applications

Composite materials (Silicon + glass wafer etc), ceramics, etc.

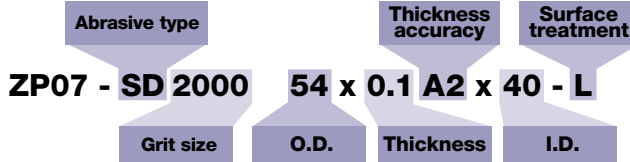


ISO 9001
JQA-0954



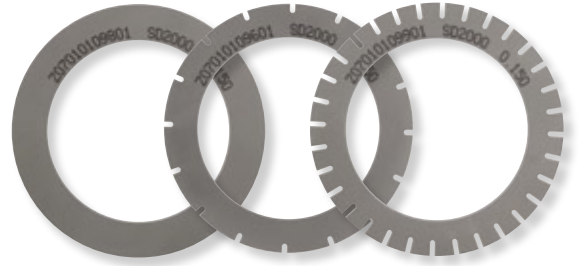
REGISTERED ORGANIZATION
No. E892-ISO14001

Specifications



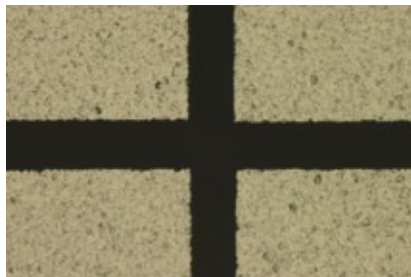
NEW Electroformed Bond Blades

ZP07 SERIES

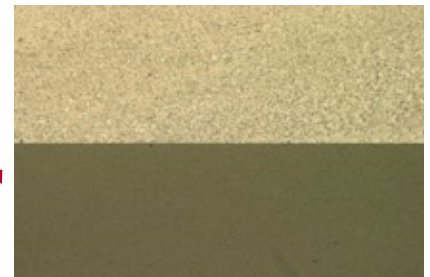


Experimental Data

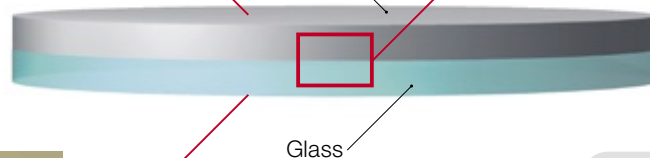
The ZP07 series can process laminated wafers (Silicon + glass) in one pass and can achieve high-grade results on the Silicon, glass and bonded surfaces.



Silicon surface



Bonded surface



Glass

Workpiece : Si 0.5 mmt + Glass 0.5 mmt
Speed : 5 mm/s
Spindle rpm : 30,000 rpm
Blade : New ZP-SD2000
Current NBC-ZB1050
Blade size : 56 x 0.1 x 40



**Reference photo
(Current Electroformed Bond Blade)**

With the current electroplated blade, the processing load increases and both blade and wafer break.

When ordering

Please contact a Disco representative with your product needs such as type, thickness, outer and inner diameter, and quantity.

When you place the first order with us, please explain application information such as materials to cut or grind, sizes, shape, machine, type, and other specification.

We are ready to help you to determine which is our most appropriate product type for your application.

Due to improvements in our products, it is possible that product specifications may be changed without advanced notice.
Please confirm the product specifications with a Disco representative.



To use these Disco wheels safely...

Please read carefully and follow the instructions below to prevent any accidents or injuries.

- USE a safety cover (nozzle case, cover), equipped as a standard accessory, to avoid injury.
- DO NOT EXCEED the maximum rpm if it is specified.
- FOLLOW the instruction manual of the machine to mount wheel properly.
- DO NOT DROP OR HIT wheels. this may cause wheel breakage or injury.
- Always CHECK the wheel for chipping or any other wheel damage before starting to use the wheel. DO NOT USE the wheel if there is any damage.
- READ the operation manual of the cutting/ grinding equipment before use.
- DO NOT USE a wheel with a modified or customized equipment.
- DO NOT USE a wheel that has a different size from the one recommended for your machine.
- DO NOT USE a wheel for any other purpose than Grinding, Cutting, or Polishing.
- Always USE water or coolant to prevent wheel breakage.

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